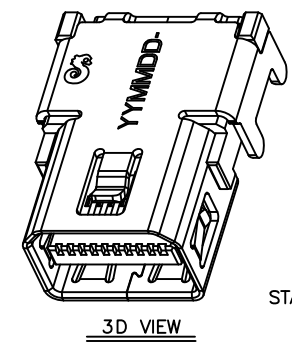
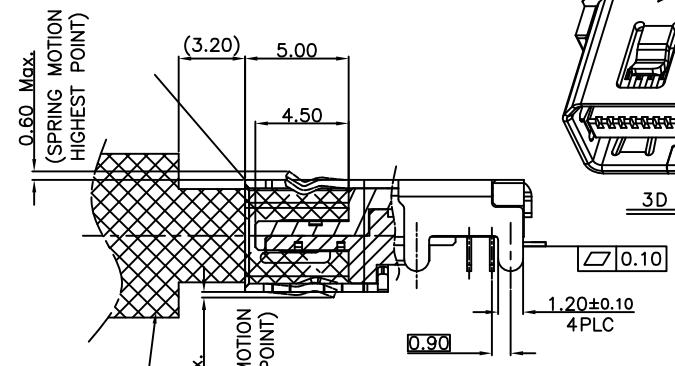
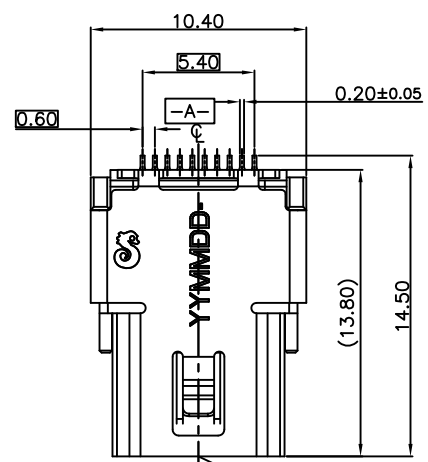
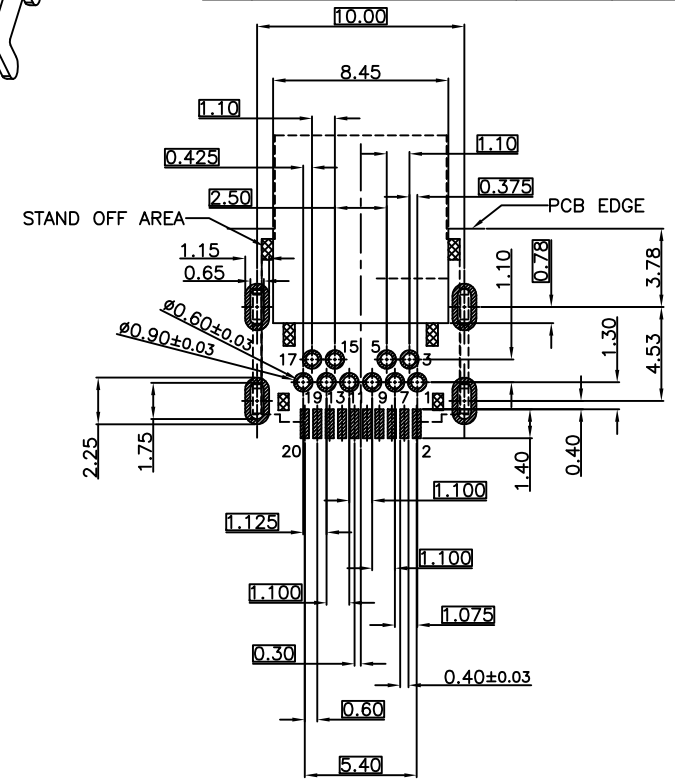


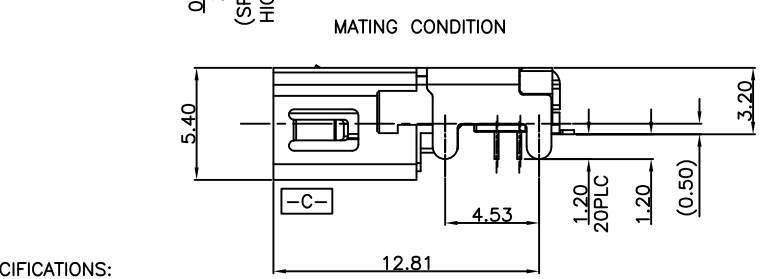
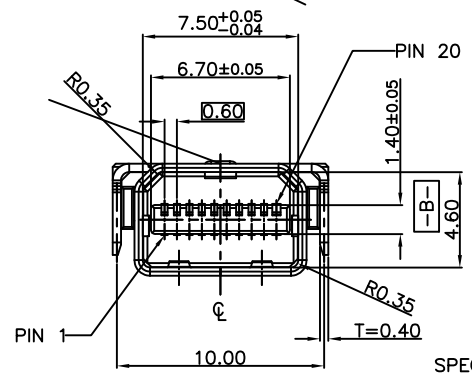
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: S120615-5A	BOYE.QI	2013.07.15
B	ECN NO: S140112	ERIC	2014.04.24
C	ECN NO: S140935	ERIC	2015.03.16



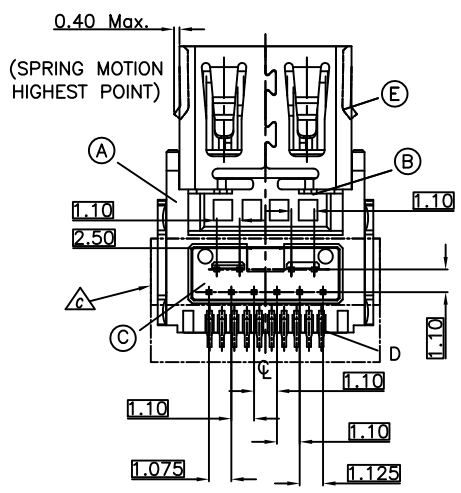
3D VIEW



Recommended P.C.B Layout(THK:1.0mm)  
TOLERANCE=±0.05



MATING CONDITION



SPECIFICATIONS:

- ELECTRICAL CHARACTERISTICS:
  - CONTACT RESISTANCE: INITIAL CONTACT RESISTANCE<100mΩ. (CHANGE FROM INITIAL VALUE=30mΩ MAX.)
  - CURRENT RATING: 0.5A.
  - VOLTAGE RATING: 40VAC.
  - INSULATION RESISTANCE: 100MΩ MIN.
  - DIELECTRIC WITHSTANDING VOLTAGE:  
UNMATED CONNECTOR: 500V AC FOR ONE MINUTE.  
MATED CONNECTOR: 300V AC FOR ONE MINUTE.
- MECHANICAL CHARACTERISTICS:
  - INSERTION FORCE : 4.5 Kg Max.
  - WITHDRAWAL FORCE : 4.0 Kg Max.  
INITIAL : 1.0Kgf.  
TEST AFTER : 0.50Kgf.
- LIFE TEST: 10000 CYCLES MIN.
- OTHER GENERAL SPEC. TO REFER "2MY3005-000111F SPEC".
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
- FOR REFLOW SOLDERING LEAD-FREE PROCESS.



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
E	SHELL	1	STAINLESS STEEL,T=0.40	NICKEL 60u"MIN
D	CONTACT	20	COPPER ALLOY, T=0.20	GOLD PLATING ON MATING AREA, Mett. Sn 100uin Min.PLATED ON SOLDERING 60uin NICKEL UNDER PLATING OVERALL
C	COVER	1	HIGH TEMP.THERMOPLASTIC	BLACK
B	SPACER	1	HIGH TEMP.THERMOPLASTIC	BLACK
A	BODY	1	HIGH TEMP.THERMOPLASTIC	BLACK
UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS: ANGLES:		TITLE		
X :±0.5	X :±2°	0.60 P 20 POS. CH=0.50mm RVS TYPE MDP CONNCTOR		
X.X :±0.3	X.X :±1°	DWN	ERIC	PART NO: 2MY3005-000111F
X.XX :±0.2		CHKD	BOYE	SCALE:4:1 UNIT: mm
		APVD	LIAO	SIZE: A3 SHEET:1 OF 1 REV:C
<b>CUSTOMER COPY</b>				